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PATENT & TRADEMARK OFFICE
INFORMATION DISCLOSURE STATEMENT

Atty. Docket No.: 110.01100101	Serial No.: 10/019,521
Applicant: Peter J. Schiller	Confirmation N.: 2112
Filing Date: December 27, 2001	Group: Unassigned
Information Disclosure Statement mailed:	August 15, 2002

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
JP	4,784,721	11/15/88	Holmen et al.	216	2	
JP	4,996,082	02/26/91	Guckel et al.	427	99	
JP	5,209,119	05/11/93	Polla et al.	73	723	1
JP	5,332,469	07/26/94	Mastrangelo	216	2	TECHNOLOGY
JP	5,438,875	08/08/95	Fung et al.	73	721	APR 22 2003
JP	5,466,932	11/14/95	Young et al.	250	299	RECEIVED
JP	5,656,778	08/12/97	Roszhart	73	504.04	JULY 22 2003
JP	5,672,551	09/30/97	Fung	438	53	RECEIVED
JP	5,707,077	01/13/98	Yokota et al.	280	735	2000
JP	5,725,785	03/10/98	Ishida et al.	216	2	1
JP	5,802,684	09/08/98	Fujii et al.	29	25,35	
JP	5,831,162	11/03/98	Sparks et al.	73	504,12	—

FOREIGN-PATENT-DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
JP	DE 42 27 819 A1	02/25/93	Germany			X	
JP	JP 2-33974	05/02/90	EPO (with English language abstract)			X	
JP	JP 09 237903 A	09/09/97	Japan (with English language abstract)				X
JP	WO 01/00523 A1	01/04/01	PCT			N/A	

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

Examiner Initial	Document Description
JP	Catling, "High-sensitivity silicon capacitive sensors for measuring medium-vacuum gas pressures," <i>Sensors and Actuators A</i> , 1998; 64:157-164.

EXAMINER

[Signature]

Date Considered

10/21/03

* Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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Examiner Initial	Document Description
J	French, "Development of surface micromachining techniques compatible with on-chip electronics," <i>J. Micromech. Microeng.</i> , 1996; 6:197-211.
J	Fung et al., "Multifunction Polysilicon Pressure Sensors for Process Control," <i>Sensors</i> , 1999 Oct.; 16(10):75-79, 83.
J	Kwon et al., "Three Axis Piezoresistive Accelerometer Using Polysilicon Layer," <i>Transducers '97</i> , International Conference on Solid-State Sensors and Actuators, Chicago, Ill., June 16-19 1997; 1221-1188.
J	Lee et al., "Piezoelectric Cantilever Microphone and Microspeaker," <i>J. of Microelectromechanical Systems</i> , 1996 Dec.; 5(4):238-242.
J	Lemkin et al., "A 2-Axis Force Balanced Accelerometer Using a Single Proof-Mass," <i>Transducters '97</i> , International Conference on Solid-State Sensors and Actuators, Chicago, Ill., 1997; 1185-1224.
J	Lutz et al., "A Precision Yaw Rate Sensor in Silicon Micromachining," <i>Transducters '97</i> , International Conference on Solid-State Sensors and Actuators, Chicago, Ill., 1997; 847-850.
J	Pedersen et al., "An integrated silicon capacitive microphone with frequency-modulated digital output," <i>Sensors and Actuators A</i> , 1998; 69:267-275.
J	Wolf et al., <i>Silicon Processing for the VLSI Era</i> , Sunset Beach, Calif.-Lattice Press, Lattice Press, Sunset Beach, Cali., 1986, Cover Page, Publication Page, and Table of Contents only. (12 pgs.)
J	Yazdi et al., "An All-Silicon single-wafer fabrication technology for precision microaccelerometers," <i>Transducters '97</i> , International Conference on Solid-State Sensors and Actuators, Chicago, Ill., 1997; 1181-1184.
J	Yeh et al., "A Low-Voltage Tunneling-Based Silicon Microaccelerometer," <i>IEEE Transactions on Electron Devices</i> , 1997 Nov.; 44(11):1875-1882.

EXAMINER <i>Jesse</i>	Date Considered <i>10/21/03</i>
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